



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Byung Hoon Ahn, Jae Hun Ku, Young Suk Chung, Suk Gu Ko, Sung Sik Jang, Young Nam Choi, Won Chul Do

Assignee: Amkor Technology, Inc.

Title: Lead Frame And Semiconductor Package Made Using The Leadframe

Serial No.: 09/845,601 Filing Date: April 26, 2001

Examiner: Not Yet Assigned Group Art Unit: 2811

Docket No.: AB-1134 US

San Jose, California  
August 29, 2001

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Attn: Official Draftsperson  
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**SUBMISSION OF FORMAL DRAWINGS**

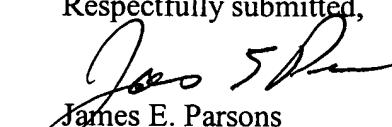
Dear Sir:

Applicants submit 7 sheets of formal drawings, consisting of Figures 1a, 1b, 1c, 2a, 2b, 3a, 3b, 3c, 4a, 4b, 5a, 5b, 6a, and 6b, in the above-named application. If there are any questions regarding these drawings, please call the undersigned at (408) 453-9200.

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Respectfully submitted,

  
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